

FEATURES

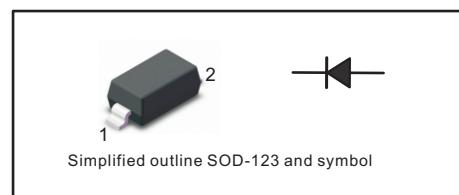
- For surface mounted applications
- Glass Passivated Chip Junction
- Fast reverse recovery time
- Ideal for automated placement
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- Case: SOD-123
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 16mg/0.00056oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode


Absolute Maximum Ratings at 25 °C

Parameter	Symbols	BAV19W	BAV20W	BAV21W	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	120	200	250	V
Maximum RMS voltage	V_{RMS}	100	150	200	V
Continuous Forward Current	I_F		250		mA
Repetitive Peak Forward Current	I_{FRM}		625		mA
Non-repetitive Peak Forward Surge Current at 1s at 1ms at 1 us	I_{FSM}		1 3 9		A
Total Power Dissipation	P_{tot}		500		mW
Operating and Storage Temperature Range	T_j, T_{stg}		-55 ~ +150		°C

Characteristics at $T_a = 25$ °C

Parameter	Symbols	BAV19W	BAV20W	BAV21W	Units
Reverse Breakdown Voltage at $I_R=100\mu A$	$V_{(BR)R}$	120	200	250	V
Maximum Forward Voltage at 100 mA at 200 mA	V_F		1.00 1.25		V
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_a = 25$ °C $T_a = 150$ °C	I_R		0.1 100		μA
Typical Junction Capacitance at $V_R=4V$, $f=1MHz$	C_J		5		pF
Maximum Reverse Recovery Time ⁽¹⁾	t_{rr}		50		ns

(1) Measured with $I_F = 0.5$ A, $I_R = 1$ A, $I_{RR} = 0.25$ A

Fig.1 Forward Current Derating Curve

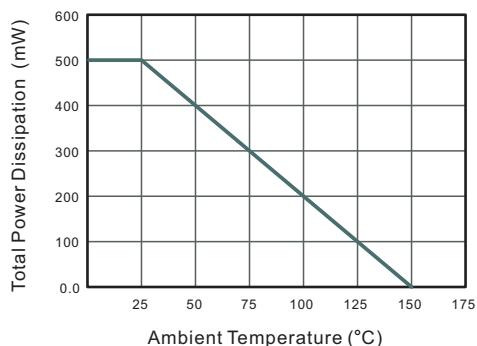


Fig.2 Typical Reverse Characteristics

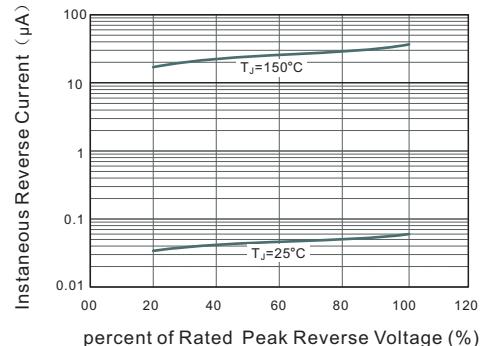


Fig.3 Typical Instaneous Forward Characteristics

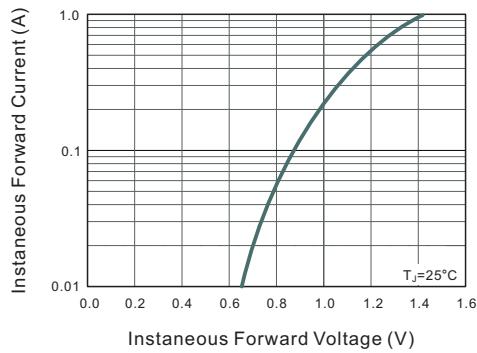
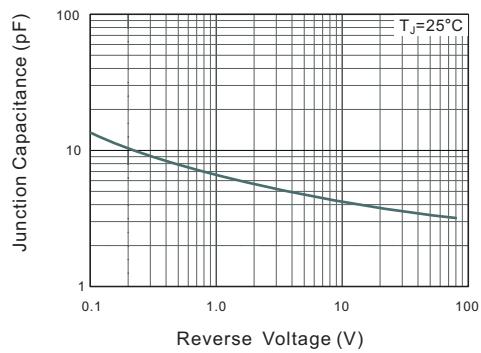


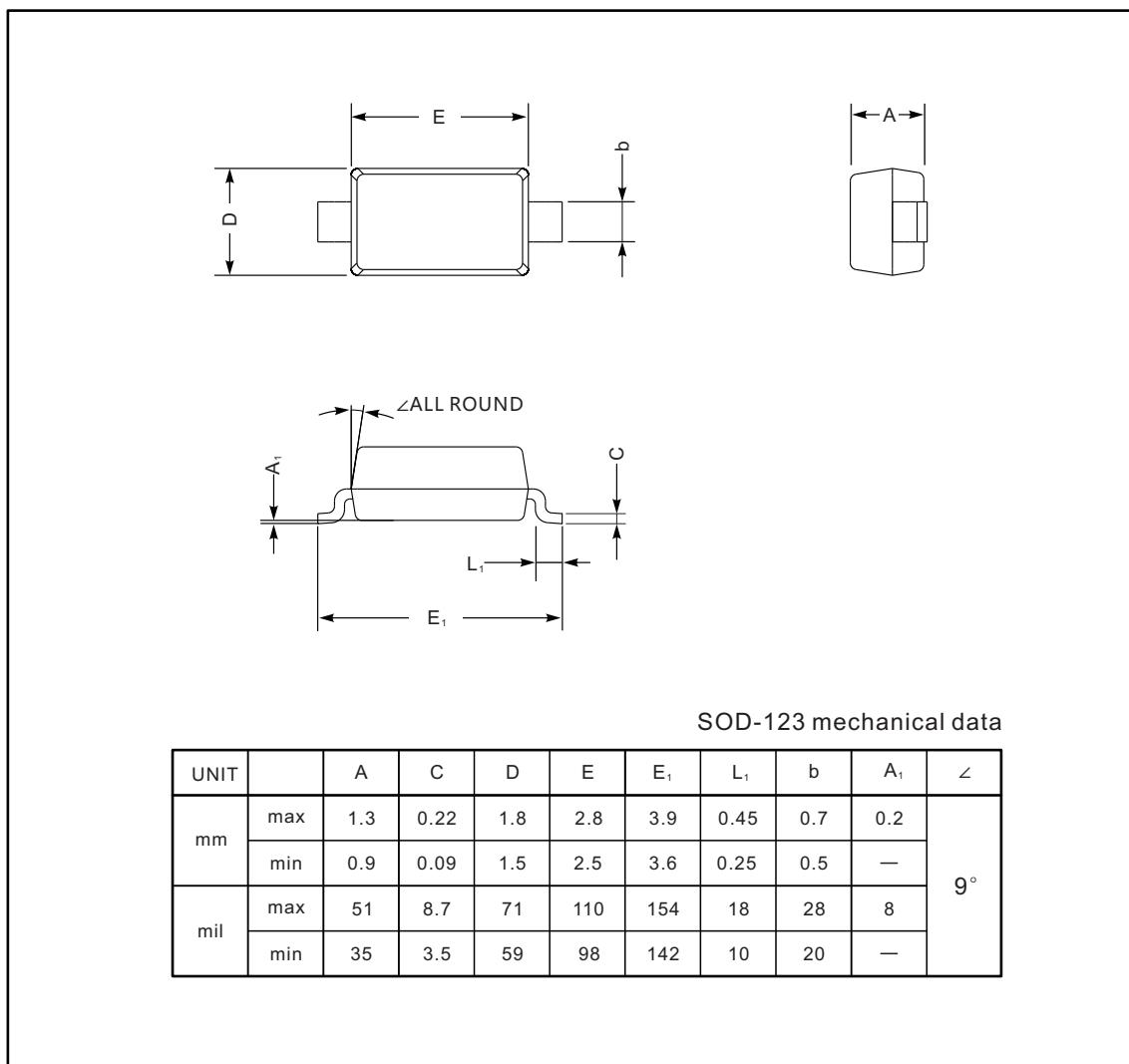
Fig.4 Typical Junction Capacitance



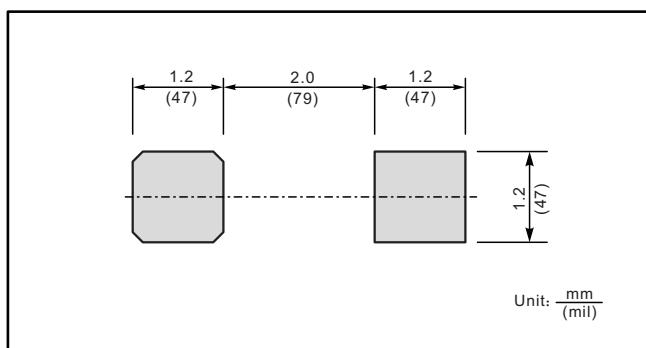
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-123



The recommended mounting pad size



Marking

Type number	Marking code
BAV19W	A8
BAV20W	T2
BAV21W	T3